

IMP5218

9-Line SCSI Terminator Plug and Play

DESCRIPTION

The IMP5218 terminator is part of IMP's SCSI terminator family of high-performance, adaptive, non-linear mode SCSI products, which are designed to deliver true UltraSCSI performance in SCSI applications. The low voltage BiCMOS architecture employed in its design offers performance superior to older linear passive and active techniques. IMP's SCSI terminator architecture employs high-speed adaptive elements for each channel, thereby providing the fastest response possible — typically 35MHz, which is 100 times faster than the older linear regulator/terminator approach used by other manufacturers. Products using this older linear regulator approach have bandwidths which are dominated by the output capacitor and which are limited to 500KHz (see further discussion in the Functional Description section). This new architecture also eliminates the output compensation capacitor required in earlier terminator designs. Each is approved for use with SCSI-1, -2, -3, UltraSCSI and beyond — providing the highest performance alternative available today.

Another key improvement offered by the IMP5218 lies in its ability to insure reliable, error free communications even in systems which do not adhere to recommended SCSI hardware design

guidelines, such as the use of improper cable lengths and impedances. Frequently, this situation is not controlled by the peripheral or host designer and, when problems occur, they are the first to be made aware of the problem. The IMP5218 architecture is much more tolerant of marginal system integrations.

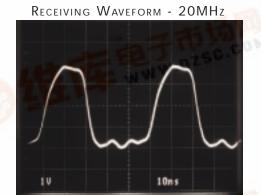
The IMP5218 has two disconnect pins for SCSI Plug and Play (PnP) applications. Quiescent current is typically less than 275µA in this mode, while the output capacitance is also less than 3pF. The obvious advantage of extended battery life for portable systems is inherent in the product's disable-mode feature. Additionally, the disable function permits factory-floor or production-line configurability, reducing inventory and product-line diversity costs. Field configurability can also be accomplished without physically removing components which, often times results in field returns due to mishandling.

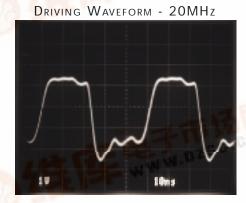
Reduced component count is also inherent in the IMP5218 architecture. Traditional termination techniques require large stabilization and transient protection capacitors of up to $20\mu F$ in value and size. The IMP5218 architecture does not require these components, allowing all the cost savings associated with reduced inventory, board space, and assembly, plus higher reliability.

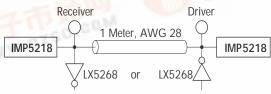
KEY FEATURES

- SCSI PLUG AND PLAY, DUAL LOW
 DISCONNECT, LOGIC LOW COMMAND DISCONNECTS ALL TERMINATION LINES
- HOT SWAP COMPATIBLE
- ULTRA-FAST RESPONSE FOR FAST-20 SCSI APPLICATIONS
- 35MHz CHANNEL BANDWIDTH
- 3.5V OPERATION
- LESS THAN 3pf OUTPUT CAPACITANCE
- DISABLE-MODE CURRENT LESS THAN 275µA
- THERMALLY SELF LIMITING
- <u>NO</u> EXTERNAL COMPENSATION CAPACITORS
- IMPLEMENTS 8-BIT OR 16-BIT (*WIDE*) APPLICATIONS
- COMPATIBLE WITH ACTIVE NEGATION DRIVERS (60mA / CHANNEL)
- COMPATIBLE WITH PASSIVE AND ACTIVE TERMINATIONS
- APPROVED FOR USE WITH SCSI 1, 2, 3
 AND ULTRASCSI

PRODUCT HIGHLIGHT







PACKAGE ORDER INFORMATION

Т _, (°С)	DW Plastic SOWB 16-pin	PW Plastic TSSOP 20-pin		
0 to 125	IMP5218CDW	IMP5218CPW		

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Note: All surface-mount packages are available in Tape & Reel. Append the letter "T" to part number. (i.e. IMP5218CDWT)

ABSOLUTE MAXIMUM RATINGS (Note 1)

Continuous Termination Voltage	10V
Continuous Output Voltage Range	
Continuous Disable Voltage Range	0 to 5.5V
Operating Junction Temperature	
Storage Temperature Range	65°C to +150°C
Solder Temperature (Soldering, 10 seconds)	300°C

Note 1. Exceeding these ratings could cause damage to the device.

THERMAL DATA

DW PACKAGE:

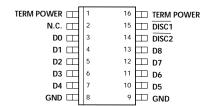
PW PACKAGE:

THERMAL RESISTANCE-JUNCTION TO AMBIENT, $Q_{_{JA}}$ 144°C/W

Junction Temperature Calculation: $T_{_J} = T_{_A} + (P_{_D} \ x \ \theta_{_{JA}})$. The $\theta_{_{JA}}$ numbers are guidelines for the thermal performance of the device/pc-board system.

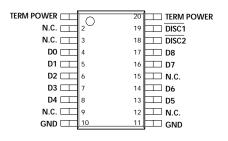
All of the above assume no ambient airflow.

PACKAGE PIN OUTS



DW PACKAGE

(Top View)



PW PACKAGE (Top View)

RECOMMENDED OPERATING CONDITIONS (Note 2)

D	C	Recommended Operating Conditions			11
Parameter	Symbol	Min.	Тур.	Max.	Units
Termination Voltage	V _{TERM}	3.5		5.5	V
High Level Disable Input Voltage	V _{IH}	2		V _{TERM}	V
Low Level Disable Input Voltage	V _{IL}	0		0.8	V
Operating Virtual Junction Temperature Range		0		125	°C

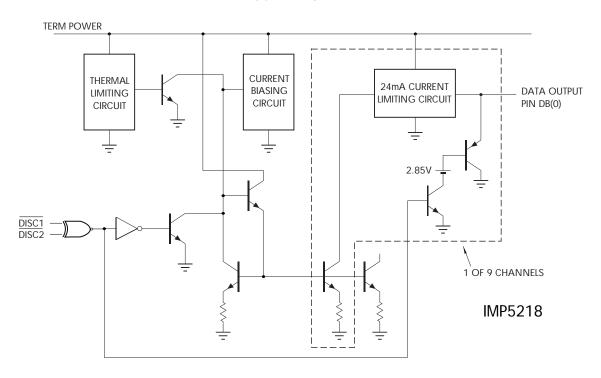
Note 2. Range over which the device is functional.

ELECTRICAL CHARACTERISTICS

Term Power = 4.75V unless otherwise specified. Unless otherwise specified, these specifications apply at the recommended operating ambient temperature of $T_A = 25$ °C. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

Davamatar	Symbol	Test Conditions	IMP5218			Limita
Parameter			Min.	Тур.	Max.	Units
Output High Voltage	V _{OUT}		2.65	2.85		V
TermPwr Supply Current	I _{cc}	All data lines = open		6	9	mA
		All data lines = 0.5V		215	225	mA
		$\overline{\text{DISC1}} = \overline{\text{DISC2}} = \text{OV}$		275		μΑ
Output Current	l _{оит}	$V_{OUT} = 0.5V$	-21	-23	-24	mA
Disable Input Current	I _{IN}	$\overline{\text{DISC1}} = \overline{\text{DISC2}} = 4.75V$		90		μΑ
		$\overline{\text{DISC1}} = \overline{\text{DISC2}} = \text{OV}$		-10		nA
Output Leakage Current		$\overline{\text{DISC1}} = \overline{\text{DISC2}} = \text{OV}, V_{\text{O}} = 0.5\text{V}$		10		nA
Capacitance in Disabled Mode	Соит	V _{OUT} = 0V, frequency = 1MHz		3		рF
Channel Bandwidth	BW			35		MHz
Termination Sink Current, per Channel	I _{SINK}	$V_{OUT} = 4V$		60		mA

BLOCK DIAGRAM



FUNCTIONAL DESCRIPTION

Cable transmission theory suggests to optimize signal speed and quality, the termination should act both as an ideal voltage reference when the line is released (deasserted) and as an ideal current source when the line is active (asserted). Common active terminators, which consist of Linear Regulators in series with

resistors (typically 110Ω), are a compromise. As the line voltage increases, the amount of current decreases linearly by the equation V = I * R. The IMP5218, with its unique new architecture applies the maximum amount of current regardless of line voltage until the termination high threshold (2.85V) is reached.

Acting as a near ideal line terminator, the IMP5218 closely reproduces the optimum case when

the device is enabled. To enable the device the $\overline{DISC1}$ and $\overline{DISC2}$ Pins must be pulled logic **High**, **Open**, or any combination of both **High** and **Low**. During this mode of operation, quiescent current is 6mA and the device will respond to line

Power Up / Power Down Function Table

DISC1	DISC2	Outputs	Quiescent Current
Н	Н	Enabled	6mA
Н	L	Enabled	6mA
L	Н	Enabled	6mA
L	L	Disabled	275μΑ
Open	Open	Enabled	6mA

demands by delivering 24mA on assertion and by imposing 2.85V on deassertion. In order to disable the device, the $\overline{DISC1}$ and $\overline{DISC2}$ pins must be driven logic Low. This mode of operation places the device in a sleep state where a meager 275 μ A of quiescent current is consumed. Additionally, all outputs are in a

Hi-Z (impedance) state. Sleep mode can be used for power conservation or to completely eliminate the terminator from the SCSI chain. In the second case, termination node capacitance is important to consider. The terminator will appear as a parasitic distributed capacitance on the line, which can detract from bus performance. For this reason, the IMP5218 has been optimized to have only 3pF of capacitance per output in the sleep state.

An additional feature of the IMP5218 is its compatibility with active negation drivers. The device handles up to 60mA of sink current for drivers which exceed the 2.85V output **High.**

GRAPH / CURVE INDEX

Waveforms

FIGURE

- 1A. RECEIVING WAVEFORM (Freq. = 1.0MHz)
- **1B**. DRIVING WAVEFORM
- 2A. RECEIVING WAVEFORM (Freq. = 5.0MHz)
- 2B. DRIVING WAVEFORM
- 3. 10MHz WAVEFORM
- 4. 20MHz WAVEFORM

Characteristic Curves

FIGURE

- 5. OUTPUT HIGH VOLTAGE vs. JUNCTION TEMPERATURE
- 6. OUTPUT CURRENT vs. JUNCTION TEMPERATURE
- 7. OUTPUT CURRENT vs. OUTPUT HIGH VOLTAGE ($V_T = 4.75V$)
- 8. OUTPUT CURRENT vs. OUTPUT HIGH VOLTAGE ($V_T = 3.3V$)
- 9. TERMINATION VOLTAGE vs. SUPPLY CURRENT
- 10. TERMPWR SUPPLY CURRENT vs. TERMINATION VOLTAGE (Disabled)
- 11. OUTPUT HIGH VOLTAGE vs. JUNCTION TEMPERATURE ($V_T = 3.3V$)
- 12. OUTPUT CURRENT vs. JUCTION TEMPERATURE ($V_T = 3.3V$)
- 13. OUTPUT HIGH VOLTAGE vs. TERMINATION VOLTAGE
- 14. OUTPUT CURRENT vs. TERMINATION VOLTAGE
- 15. OUTPUT CURRENT MATCHING CHANNEL TO CHANNEL

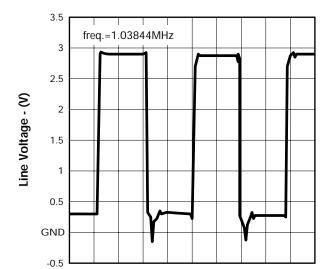
FIGURE INDEX

Application Circuits

FIGURE

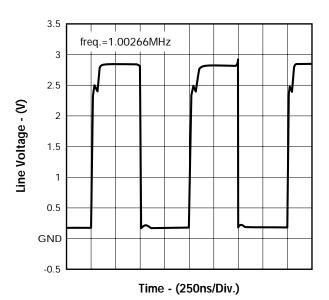
16. 8-BIT SCSI SYSTEM APPLICATION

FIGURE 1A. — RECEIVING WAVEFORM



Time - (250ns/Div.)

FIGURE 1B. — DRIVING WAVEFORM



END-DRIVEN CABLE

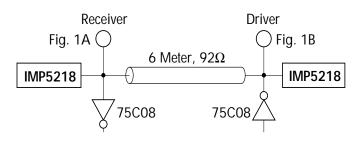
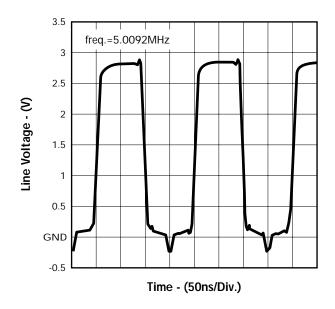
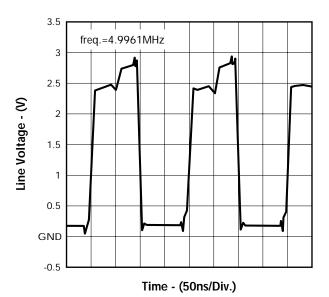


FIGURE 2A. — RECEIVING WAVEFORM







END-DRIVEN CABLE

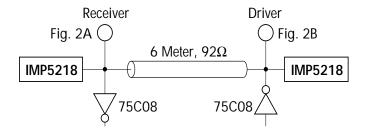
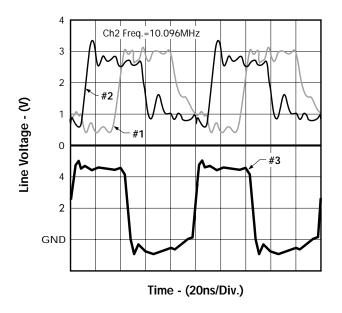
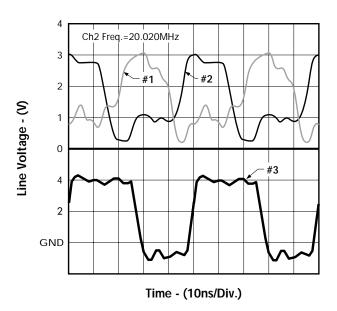


FIGURE 3. — 10MHz WAVEFORM

FIGURE 4. — 20MHz WAVEFORM





END-DRIVEN CABLE

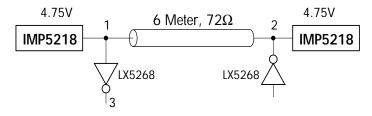


FIGURE 5. — OUTPUT HIGH VOLTAGE vs. JUNCTION TEMP.

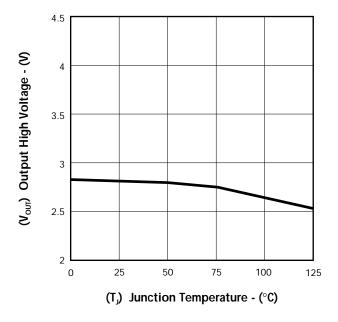


FIGURE 6. — OUTPUT CURRENT vs. JUNCTION TEMP.

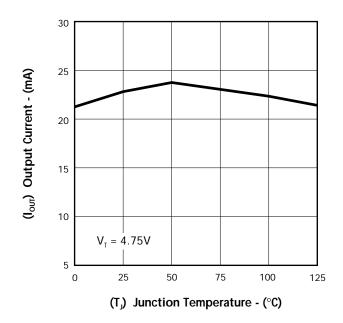


FIGURE 7. — OUTPUT CURRENT vs. OUTPUT HIGH VOLTAGE

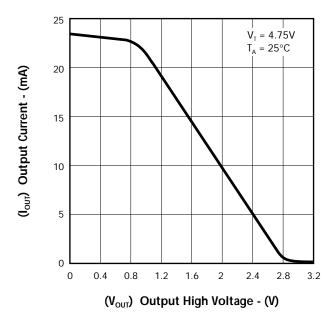


FIGURE 8. — OUTPUT CURRENT vs. OUTPUT HIGH VOLTAGE

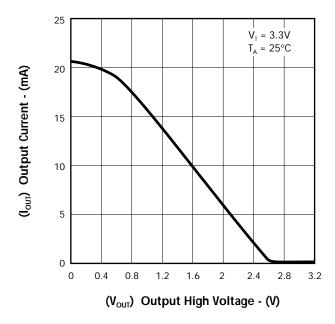


FIGURE 9. — TERMPWR SUPPLY CURRENT vs. TERMINATION VOLTAGE

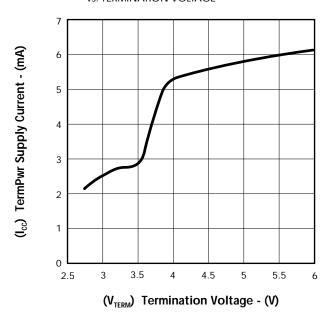


FIGURE 10. — TERMPWR SUPPLY CURRENT vs. TERMINATION VOLTAGE (Disabled)

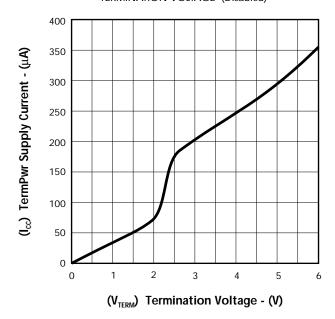


FIGURE 11. — OUTPUT HIGH VOLTAGE vs. JUNCTION TEMP.

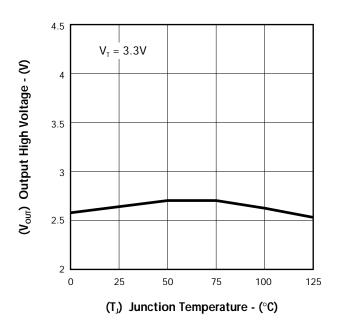


FIGURE 12. — OUTPUT CURRENT vs. JUNCTION TEMP.

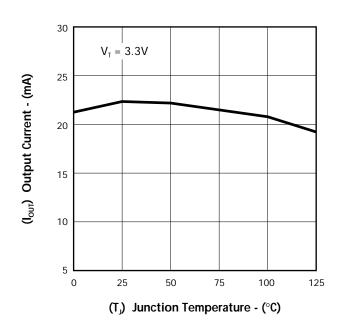


FIGURE 13. — OUTPUT HIGH VOLTAGE vs. TERMINATION VOLTAGE

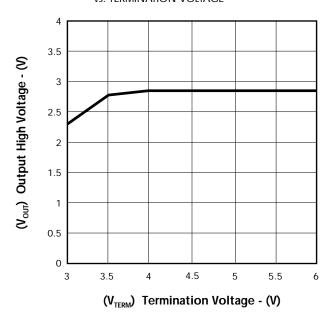


FIGURE 14. — OUTPUT CURRENT vs. TERMINATION VOLTAGE

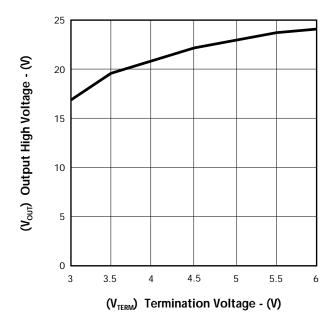
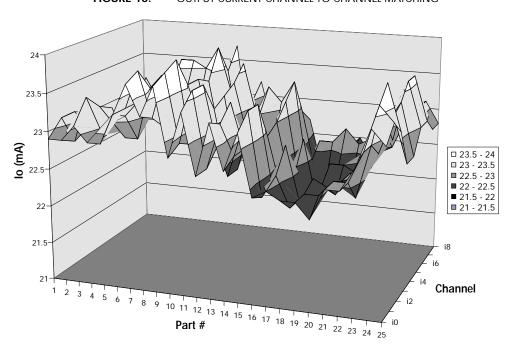
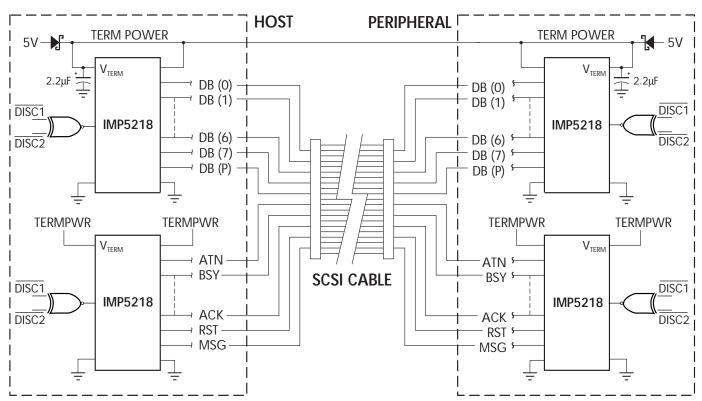


FIGURE 16. — OUTPUT CURRENT CHANNEL TO CHANNEL MATCHING



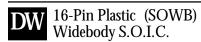
APPLICATION SCHEMATIC

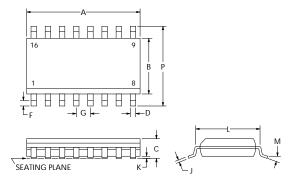
FIGURE 17 — 8-BIT SCSI SYSTEM APPLICATION



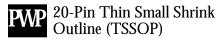
Note: Add third IMP5218 for 16-bit SCSI

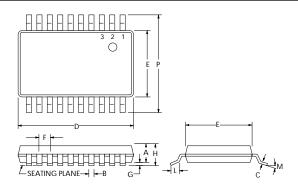
PACKAGE DIMENSIONS





	MILLIN	INCHES				
DIM	MIN	MAX	MIN	MAX		
Α	_	10.67	_	0.420		
В	7.49	7.75	0.295	0.305		
С	2.35	2.65	0.093	0.104		
D	0.25	0.46	0.010	0.018		
F	0.64	0.89	0.025	0.035		
G	1.27 BSC		0.050	O BSC		
J	0.23	0.32	0.009	0.013		
K	0.10	0.30	0.004	0.012		
L	8.13	8.64	0.320	0.340		
M	0°	8°	0°	8°		
Р	10.26	10.65	0.404	0.419		
	* See NOTF: 1					





MILLIMETERS			INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	_	0.90	_	0.354	
В	0.18	0.30	0.0071	0.0118	
С	0.90	0.180	0.0035	0.0071	
D	6.40	6.60	0.252	0.260	
Ε	4.30	4.48	0.169	0.176	
F	0.65	0.65 BSC		5 BSC	
G	0.05	0.15	0.002	0.005	
Н	_	1.10	_	0.0433	
L	0.50	0.70	0.020	0.028	
M	0°	8°	0°	8°	
P	6.25	6.50	0.246	0.256	



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Document Number: IMP5218-02-10/97